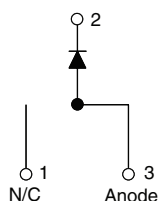


HEXFRED®

Ultrafast Soft Recovery Diode, 16 A



D²PAK

FEATURES

- Ultrafast recovery
- Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- Specified at operating conditions
- Designed and qualified for industrial level

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

HFA16TB120S is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 16 A continuous current, the HFA16TB120S is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA16TB120S is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY

V_R	1200 V
V_F at 16 A at 25 °C	3 V
$I_{F(AV)}$	16 A
t_{rr} (typical)	30 ns
T_J (maximum)	150 °C
Q_{rr} (typical)	260 nC
$dI_{(rec)}/dt$ (typical) at 125 °C	76 A/ μ s
I_{RRM} (typical)	5.8 A

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Cathode to anode voltage	V_R		1200	V
Maximum continuous forward current	I_F	$T_C = 100\text{ °C}$	16	A
Single pulse forward current	I_{FSM}		190	
Maximum repetitive forward current	I_{FRM}		64	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	151	W
		$T_C = 100\text{ °C}$	60	
Operating junction and storage temperature range	T_J, T_{Stg}		- 55 to + 150	°C

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 µA		1200	-	- V
Maximum forward voltage	V _{FM}	I _F = 16 A	See fig. 1	-	2.5	3.0
		I _F = 32 A		-	3.2	3.93
		I _F = 16 A, T _J = 125 °C		-	2.3	2.7
Maximum reverse leakage current	I _{RM}	V _R = V _R rated	See fig. 2	-	0.75	20
		T _J = 125 °C, V _R = 0.8 x V _R rated		-	375	2000
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	27	40 pF
Series inductance	L _S	Measured lead to lead 5 mm from package body		-	8.0	- nH

DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Reverse recovery time See fig. 5 and 10	t _{rr}	I _F = 1.0 A, dI _F /dt = 200 A/µs, V _R = 30 V		-	30	-
	t _{rr1}	T _J = 25 °C	I _F = 16 A dI _F /dt = 200 A/µs V _R = 200 V	-	90	135
	t _{rr2}	T _J = 125 °C		-	164	245
Peak recovery current See fig. 6	I _{RRM1}	T _J = 25 °C		-	5.8	10
	I _{RRM2}	T _J = 125 °C		-	8.3	15
Reverse recovery charge See fig. 7	Q _{rr1}	T _J = 25 °C		-	260	675
	Q _{rr2}	T _J = 125 °C		-	680	1838
Peak rate of fall of recovery current during t _b See fig. 8	dI _{(rec)M} /dt1	T _J = 25 °C		-	120	-
	dI _{(rec)M} /dt2	T _J = 125 °C		-	76	-

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s		-	-	300 °C
Thermal resistance, junction to case	R _{thJC}			-	-	0.83
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount		-	-	80
Weight				-	2.0	- g
				-	0.07	- oz.
Marking device		Case style D ² PAK		HFA16TB120S		

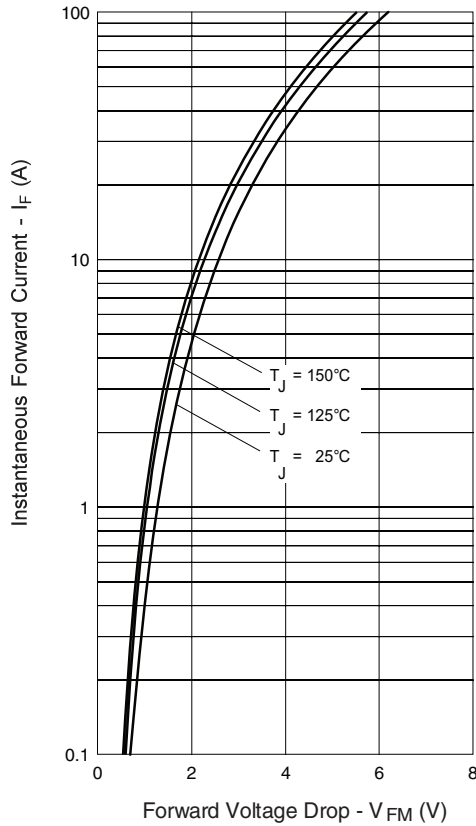


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

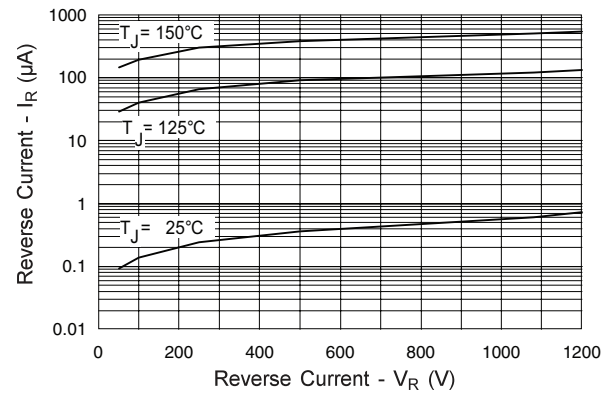


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

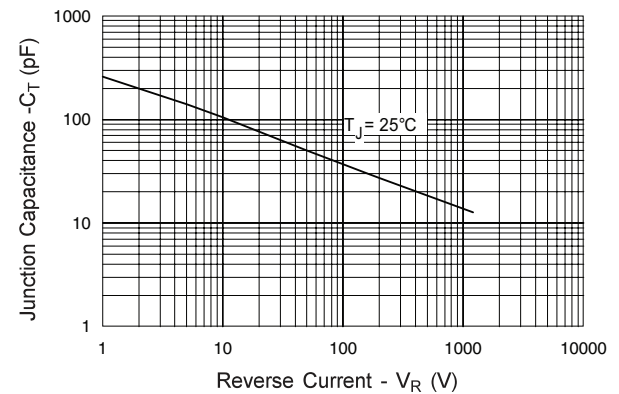


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

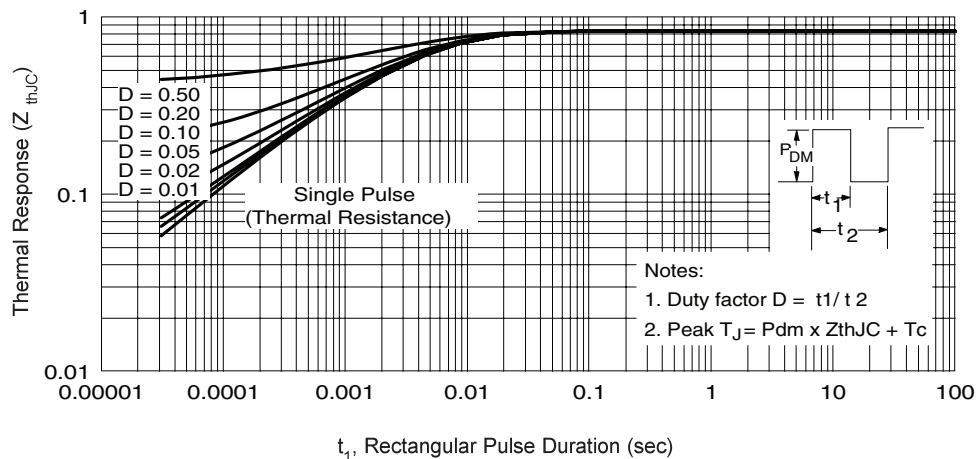
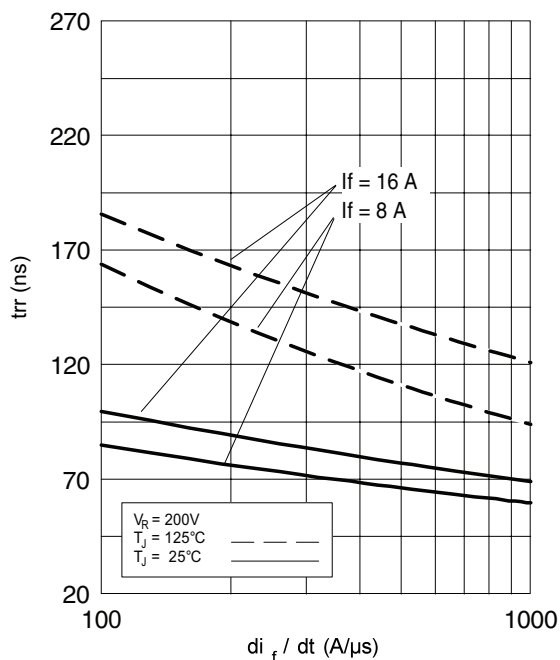
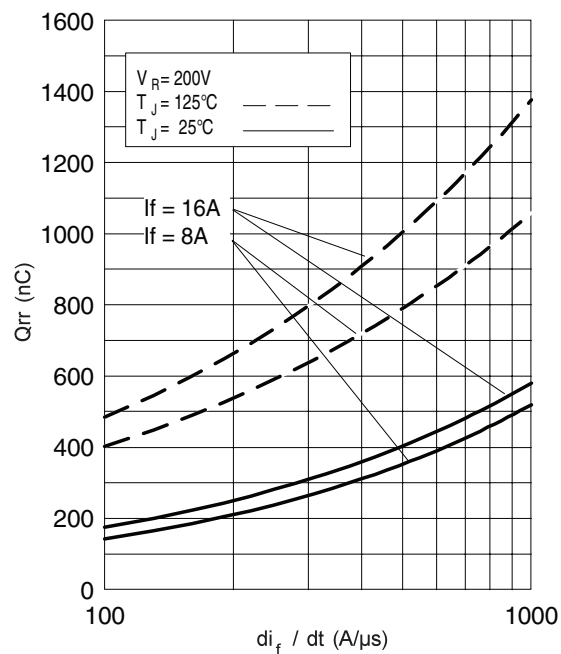
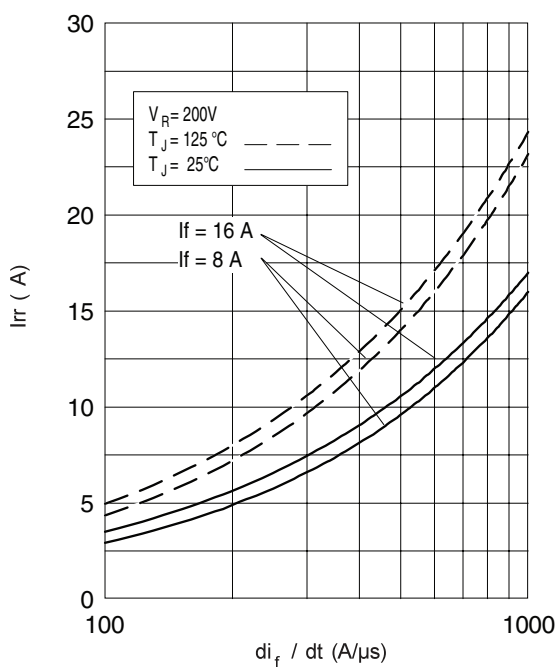
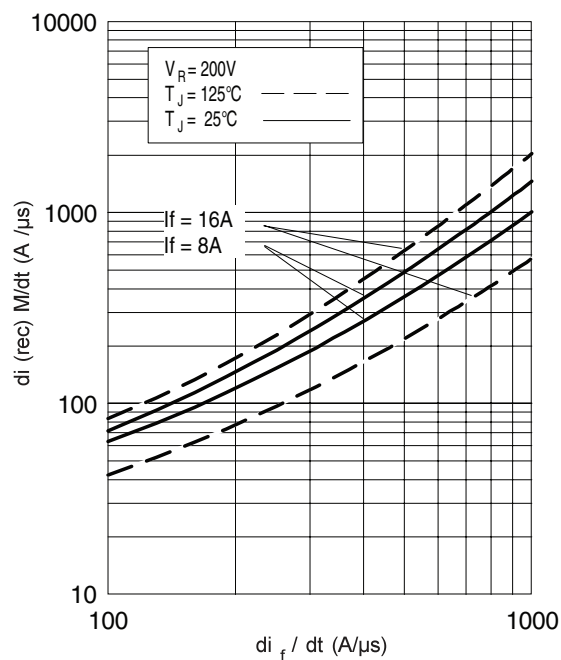


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

Fig. 5 - Typical Reverse Recovery Time vs. di_F/dt (Per Leg)Fig. 7 - Typical Stored Charge vs. di_F/dt (Per Leg)Fig. 6 - Typical Recovery Current vs. di_F/dt (Per Leg)Fig. 8 - Typical $dI_{(rec)}M/dt$ vs. di_F/dt (Per Leg)

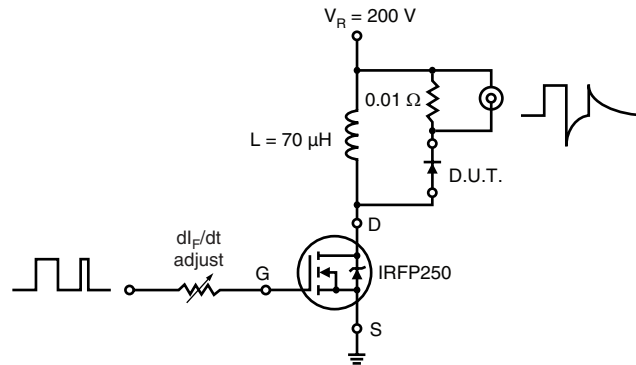


Fig. 9 - Reverse Recovery Parameter Test Circuit

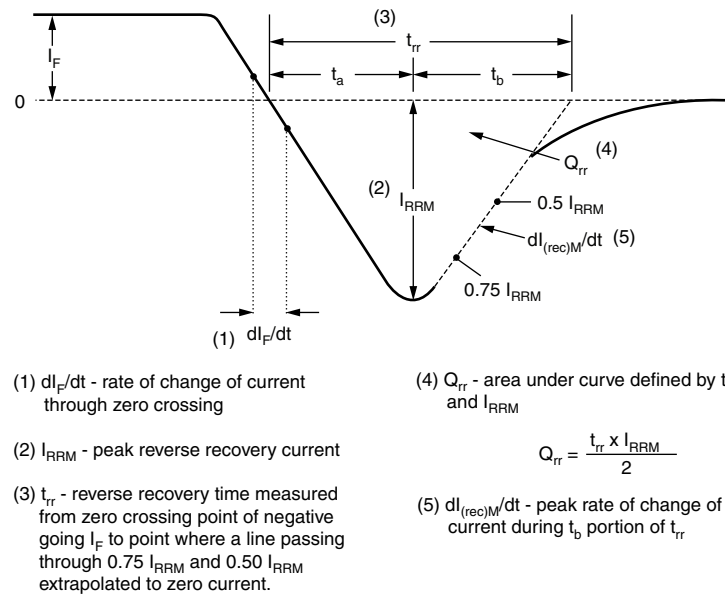


Fig. 10 - Reverse Recovery Waveform and Definitions

LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95046
Part marking information	http://www.vishay.com/doc?95054
Packaging information	http://www.vishay.com/doc?95032



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